

Material Composition Specification

SOD-323 Case

Pb (lead)-free plating**



Device average mass 4.9 mg

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.43%	0.07	Si	7440-21-3	1.43%	0.07	14,286
bond wire	gold	0.2%	0.01	Au	7440-57-5	0.2%	0.01	2,041
leadframe	Cu alloy w/ silver plating	22.82%	1.118	Cu	7440-50-8	22.37%	1.096	223,673
				Ag	7440-22-4	0.45%	0.022	4,490
encapsulation*	EMC	71.55%	3.506	silica	7631-86-9	51.59%	2.528	515,918
				epoxy resin	Proprietary	17.96%	0.88	179,592
				Sb ₂ O ₃	1309-64-4	1.43%	0.07	14,286
				TBBA	79-94-7	0.37%	0.018	3,673
				carbon black	1333-86-4	0.2%	0.01	2,041
	EMC GREEN	71.55%	3.506	silica	60676-86-0	47.63%	2.334	476,327
				epoxy resin	37382079-9	8.29%	0.406	82,857
				phenol resin	9003-35-4	8.29%	0.406	82,857
				carbon black	1333-86-4	0.2%	0.01	2,041
				metal hydroxide	1309-42-8	7.14%	0.35	71,429
plating**	tin lead process	4.0%	0.196	Sn	7440-31-5	3.41%	0.167	34,082
				Pb	7439-92-1	0.59%	0.029	5,918
	100% tin process	4.0%	0.196	Sn	7440-31-5	4.0%	0.196	40,000

*EMC GREEN molding compound is Halogen-Free.

**Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.